## **CLAIMS**

What is claimed is:

1. A moldable resin for use in a molding process to form a molded part at least partially therefrom, the moldable resin comprising:

a base resin;

a plurality of shape memory alloy (SMA) particles interspersed in said base resin; and

wherein said SMA particles are suspended in said base resin and serve to enhance a specific property of said base resin.

- 2. The moldable resin of claim 1, wherein said SMA particles comprise NITINOL® alloy particles.
- 3. The moldable resin of claim 1, wherein said SMA particles are less than about 1% of a total volume of said resin.
- 4. The moldable resin of claim 1, wherein said SMA particles comprise between about 1% and 50% by volume of said resin.
- 5. The moldable resin of claim 1, wherein said SMA particles comprise at least about 50% by volume of said resin.
- 6. The moldable resin of claim1, wherein said SMA particles comprise SMA particles in their austenitic phase.
- 7. The moldable resin of claim 1, wherein said SMA particles comprise SMA particles in their martensitic phase.
- 8. The moldable resin of claim 1, wherein said SMA particles comprise a mixture of SMA particles in martensitic and austenitic phases.

- 9. The moldable resin of claim 1, wherein said base resin comprises a thermoplastic resin.
- 10. The moldable resin of claim 1, wherein said base resin comprises a thermosetting resin.
- 11. The moldable resin of claim 1, wherein said resin is suitable for use in injection molding and compression molding processes.
- 12. The moldable resin of claim 1, wherein said SMA particles are formed in at least one of the group of shapes comprising: spherical, cylindrical and oval.
- 13. The moldable resin of claim 1, wherein said SMA particles comprise granules intermixed within said base resin.
- 14. The moldable resin of claim 1, wherein said SMA particles comprise a size of between about 0.005 micron to about 50 micron.
- 15. The moldable resin of claim 1, wherein said SMA particles comprise a size of at least about 50 microns.
- 16. The moldable resin of claim 1, wherein said SMA particles comprise a size of no more than about 0.005 micron.

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- 17. A moldable resin for use in an injection molding process to make an injection molded part, the moldable resin comprising:
- a base resin comprised of one of a thermoplastic or thermosetting plastic resin; and
- a plurality of shape memory alloy (SMA) particles added to the base resin to enhance a property of said base resin.
- 18. The moldable resin of claim 17, wherein said SMA particles are in their austenitic phase when added to the base resin.
- 19. The moldable resin of claim 17, wherein said SMA particles are in their martensitic phase when added to the base resin.
- 20. The moldable resin of claim 17, wherein said SMA particles comprise NITINOL® alloy particles.
- 21. The moldable resin of claim 17, wherein said SMA particles comprise less than about 1.0% by volume of said resin.
- 22. The moldable resin of claim 17, wherein said SMA particles comprise between about 1.0% to about 50% by volume of said resin.

- 23. A moldable resin for use in a compression molding process to make a compression molded part, the moldable resin comprising:
- a base resin comprised of one of a thermoplastic or thermosetting plastic resin; and
- a plurality of shape memory alloy (SMA) particles added to the base resin to enhance a property of said base resin without affecting a moldability of said base resin.
- 24. The moldable resin of claim 23, wherein said SMA particles comprise NITINOL® alloy particles.
- 25. The moldable resin of claim 24, wherein said NITINOL® alloy particles are provided in their austenitic phase when added to said base resin.
- 26. The moldable resin of claim 24, wherein said NITINOL® alloy particles are provided in their martensitic phase when added to said base resin.
- 27. The moldable resin of claim 23, wherein said SMA particles comprise a shape in accordance with one of the group of shapes comprising: oval, spherical and cylindrical.
- 28. The moldable resin of claim 23, wherein said SMA particles comprise granules added to said base resin.